TGP1200, 1500, 3000, 5000, 6000 and 8000 Thermal Gap Filler Pad

BENEFITS AND FEATURES

- High thermal performance
- Ultra-high compressibility for low stress applications
- Excellent surface wetting for low contact resistance
- High reliability
- Electrically insulating

OVERVIEW

Honeywell TGP series Thermal Gap Filler Pads provide high thermal performance with ease of use across multitude of applications. Its ultra-high compressibility enables low stress and excellent conformity to mating surfaces. It is designed to minimize thermal resistance at interfaces and maintain excellent performance through reliability testing. TGP series products are naturally tacky and require no additional adhesive which might weaken thermal performance. Products are available in thickness range from 0.5mm to 5.0mm.

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications & network servers
- Automotive electronics
- Power devices & modules
- Semiconductors logics & memory

STORAGE & USE

Shelf life 12 months at 0 \sim 35°C and <65% RH

Product Name	TGP 1200	TGP 1500	TGP 3000	TGP 5000	TGP 6000	TGP 8000	Test Method
Color	Blue	Grey	Yellow	Blue	Grey	Grey	Visual
Thickness (mm)*	0.5-5	0.5-5	0.5-5	0.5-5	0.5-5	0.5-5	ASTM D374
Thermal Conductivity (W/m·K)	1.2	1.5	3.0	5.0	6.0	8.0	ASTM D5470
Thermal Impedance (°C·in²/W) (1mm@10psi) (Typical Value)	1.19	0.85	0.51	0.3	0.25	0.2	ASTM D5470
Hardness (Shore00)	40	40	40	45	40	30	ASTM D2240
Density (g/cc)	1.75	1.8	3.1	3.3	3.3	3.4	ASTM D792
Dielectric Constant@1MHz	4.5	5.5	6.8	5.5	8.5	8.3	ASTM D150
Volume Resistivity (ohm·cm)	4x10 ¹²	2x10 ¹³	5x 10 ¹³	9x10 ¹³	4x10 ¹⁵	7x10 ¹⁵	ASTM D257
Flammability Rating	V-0	V-0	V-0	V-0	V-0	V-0	UL94

Please check thickness availability before order

Honeywell Electronic Materials

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